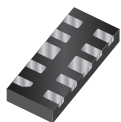


Material Composition Specification

TLM1031 Case



Device average mass 3.64 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.92%	0.07	Si	7440-21-3	1.92%	0.07	19,231
bond wire	gold	0.55%	0.02	Au	7440-57-5	0.55%	0.02	5,495
leadframe	Cu alloy	21.15%	0.77	Cu	7440-50-8	21.02%	0.765	210,165
				Cr	7440-47-3	0.05%	0.002	549
				Sn	7440-31-5	0.05%	0.002	549
				Zn	7440-66-6	0.03%	0.001	275
die attach	silver epoxy	0.25%	0.009	epoxy resin	Proprietary	0.19%	0.007	1,923
				Ag	7440-22-4	0.05%	0.002	549
encapsulation*	EMC GREEN	74.95%	2.728	silica	60676-86-0	57.69%	2.1	576,923
				epoxy resin	29690-82-2	7.14%	0.26	71,429
				phenol resin	9003-35-4	7.14%	0.26	71,429
				carbon black	1333-86-4	0.22%	0.01	2,198
				metal hydroxide	1309-42-8	2.75%	0.1	27,473
plating	matte tin	1.18%	0.043	Sn	7440-31-5	1.18%	0.043	11,813

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (3-July 2014)